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FOR IMMEDIATE RELEASE

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Greetings to our Valued SMTA Speakers and Industry Colleagues



Call for Papers 2012 for the Technology Conference

The SMTA China cordially invites you to participate in **SMTA China Conferences** located in **Chengdu, Shanghai, Wuhan, Shenzhen** for 2012. These events will address the industry's most pressing issues in electronics manufacturing, business focus, advanced packaging, emerging technologies, and lead-free & reliability.

Topical coverage includes:

Assembly: Adhesives, Alternate Alloys, BGA/CSP Assembly, Cleaning, Conformal Coating and Potting, Connector Technology, Copper Erosion, DFX/Design for Six Sigma, Dispensing, Equipment Selection, Facility Layout, Flux and Solder, Halogen and Halogen-Free, Head-in-Pillow Defect, Land Pattern Design, Lead-Free Soldering (including case studies), Lead-Free Reliability, Lean Manufacturing, Low Volume / Prototype Assembly, Medical Electronics, Placement, Printing, Reflow Soldering, Rework and Repair of QFNs, RFID Assembly, Selective Soldering, Set Up Reduction, Solder Paste, Solder Voids, Supplier Engineering, Underfill and Corner Glue, Vapor Phase Reflow for High Reliability Assemblies, Wave Soldering, Yield Improvement.

Business: Capacity Modeling, Contract Manufacturing, Doing Business in Asia, Environmental Issues, Lean Manufacturing / Quality Initiatives, Operations Management, Remaining Competitive, RoHS/REACH Compliance, Supplier Management, Technology Roadmaps.

Emerging Technologies: 0201/01005 Components and Assembly, Advanced Packaging Concepts/Applications, Consumer Applications, Electronic Printing Technology, Embedded Technology / Actives and Assembly, Flexible Electronics, MEMS/RF, MEMS/MOEMS, Nanoelectronics, Reliability of Nanodevices, New Materials and Processes, Optoelectronics, Printed Electronics, Power or Thermal Management, Sensors and Manufacturing, Solar Technology, Solid State Lighting, System in a Package, Thermal Interface Materials, and Wireless Applications including Bluetooth and Wi-Fi.



Harsh Environment Applications: Alternate Energy, Components and Component Reliability, Corrosion, Lead-free Issues for Harsh Environments, Substrates and Finishes for Harsh Environments, Thermal Management, and Tin Whiskers.

PCB Technology: Black Pad and Surface Finish Defects, Creep Corrosion, Embedded Passive and Active Components, Halogen Free, HDI, Microvias (including filled and unfilled), Moisture Sensitivity, Soldermask, Substrate Reliability, Substrate Solderability, and Surface Finish.

SMTA China solicits technical papers for presentation in the **Technology Conferences**. Inclusion in the Technology Conference requires strictly technical papers (**complimentary presentation slot for speakers**) subject to final acceptance by the Technical Advisory Committee of SMTA China. All papers including abstract and biography for inclusion in the Conference Proceedings requested in both Chinese and English. **All papers (powerpoint) suggest to be written and must presented in Chinese (translator provided by your company)**

	SMTA China West (In Chengdu)	SMTA China East (NEPCON China)
	Technology Conference 45 minute pure technical papers	19 April 2012
	SMTA China North (In Wuhan)	SMTA China South (NEPCON South China)
	Technology Conference 45 minute pure technical papers	23 August 2012

If you or your company wishes to share pertinent information with the highly qualified audience of **SMTA China** please submit your abstract to Peggy Chen by email to peggy@smta.org. Please include your name, job title, company affiliation, and all pertinent contact information **as well as your choice of Technology Conference to present your paper.**

Deadlines for **bilingual Abstract and **bilingual** Speaker Bio submission:**

SMTA China West Conference in Chengdu	1 February 2012
SMTA China East Conference in Shanghai	10 February 2012
SMTA China North Conference in Wuhan	31 May 2012
SMTA China South Conference in Shenzhen	10 June 2012

In order to appreciate the speakers of excellent information sharing, SMTA China would like to honor the best paper, and the speaker of best presentation, which award will be presented during the above SMTA events.

Thank you for your support of SMTA China and we look forward to hearing from you soon.

Best regards,

Michael YF Wong, Technical Advisory Committee Chairman of SMTA China,
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2011年11月18日

尊敬的表面装贴技术协会演讲者和业内同行



为高科技技术研讨会 2012 征集论文

SMTA 中国诚意的邀请您参加 2012 年在成都, 上海, 武汉, 深圳举办的 SMTA 高科技会议。此次会议将涉及行业中最热门的话题, 包括电子制造, 商业焦点, 新兴技术和无铅及其可靠性。

主题覆盖面包括:

装配: 粘合剂, 替用合金, BGA/CSP 装配, 清洗, 敷形涂覆与灌封, 连接器技术, 铜蚀, DFX 及六西格玛设计, 点胶, 设备选择, 工厂规划, 焊锡与助焊剂, 无卤素, 头枕缺陷, 焊盘设计, 无铅焊接(包括案例分析), 无铅的可靠性, 精益生产, 少批量与原型机装配, 医疗电子, 贴装, 锡膏印刷, 回流焊接, QFN 元件的返工与维修, 无线射频技术(RFID)装配, 选择性焊接, 快速换线设定, 锡膏, 焊接空洞, 供应工程, 底部填充与四角粘接, 用于高可靠性装配的气相回流焊接, 波峰焊接, 合格率改善。

运营: 产量模型, 合同制造, 在亚洲经商, 环境问题, 精益生产/以品质为导向, 运营管理, 保持竞争优势, 符合 RoHS/REACH 标准, 供应链管理, 技术蓝图。

新兴技术: 0201/01005 元件与装配, 高级封装概念与应用, 消费级应用, 电子印刷技术, 嵌入式技术与装配, 柔性电子, 微电子机械系统与无线射频, 微电子机械系统与微光电子机械系统, 纳米电子, 纳米技术元件的可靠性, 新材料与新工艺, 光电技术, 印刷电子, 能量与热量管理, 传感器与制造, 太阳能技术, 固态照明, 系统级封装, 热界面材料, 包括 Wi-Fi 与蓝牙的无线应用。

印刷线路板技术: 黑焊盘与表面处理缺陷, 爬行腐蚀, 嵌入式被动与主动元件, 无卤, 高密度集成, 微孔(包括填充与非填充), 湿度敏感, 阻焊层, 基材可靠性, 基材可焊性, 表面处理。

过程控制: 声学成像(C-SAM), 自动光学检查(AOI), 计算机集成制造(CIM), 在线测试(ICT), 过程建模, 软件, 测试策略和 X 光检测。



SMTA 中国为高科技技术研讨会中的演讲征集技术论文。高科技技术研讨会的技术论文主题及内容必须为纯技术论文，经由 **SMTA 中国**技术顾问委员会最终决定后，将被列入会议题目(高科技技术研讨会的演讲者无需缴付赞助费)。所有论文包括文章大纲和演讲者个人简介要求中文和英文刊登在技术论文集中。所有演讲(幻灯片形式的演讲稿)建议以中文书写但必须用中文讲解(可自备翻译)。

	SMTA 华西高科技会议 (成都)	SMTA 华东高科技会议 (上海 NEPCON 展)
高科技技术研讨会 45 分钟纯技术论文	2012 年 4 月 19 日	2012 年 4 月 25 日
	SMTA 华北高科技会议 (武汉)	SMTA 华南高科技会议 (深圳 NEPCON 华南展)
高科技技术研讨会 45 分钟纯技术论文	2012 年 8 月 23 日	2012 年 8 月 28 日

如果您和您的公司希望与 **SMTA 中国**的会员及专业观众分享贵公司的有关信息，请发邮件提交您的文章大纲给 **SMTA 中国**行政主任陈蕙小姐至 peggy@smta.org 并写上您的名字、工作头衔和公司的相关信息以及有关联系信息并且注明您的技术论文是投稿于高科技技术研讨会。

提交中英文的文章大纲和中英文的演讲者个人简介的截止日期:

SMTA 华西高科技技术研讨会(成都)	2012 年 2 月 1 日
SMTA 华东高科技技术研讨会(上海)	2012 年 2 月 10 日
SMTA 华北高科技技术研讨会(武汉)	2012 年 5 月 31 日
SMTA 华南高科技技术研讨会(深圳)	2012 年 6 月 10 日

为了感谢演讲者们优秀信息的分享, **SMTA 中国**将于以上会议中颁发最佳论文奖和最佳演讲奖以兹鼓励。

感谢您支持 **SMTA 中国**，期待您的消息。

非常感谢!

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